



Material Content Data Sheet



Sales Product Name		BTS6163D		Issued		1. August 2018			
MA#		MA001949486							
Package		PG-TO252-5-11		Weight*		355.09 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.315	0.65	0.65	6519	6519	
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		173		
	non noble metal	iron	7439-89-6	0.205	0.06		576		
	non noble metal	copper	7440-50-8	204.243	57.51	57.59	575182	575931	
	non noble metal	aluminium	7429-90-5	2.094	0.59	0.59	5896	5896	
wire	non noble metal	aluminium	7429-90-5	2.094	0.59	0.59	5896	5896	
encapsulation	organic material	carbon black	1333-86-4	1.396	0.39		3930		
	plastics	epoxy resin	-	24.422	6.88		68777		
	inorganic material	silicondioxide	60676-86-0	113.739	32.03	39.30	320306	393013	
leadfinish	non noble metal	tin	7440-31-5	5.072	1.43	1.43	14285	14285	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	215	216	
glue	plastics	Polyimide	26023-21-2	0.143	0.04	0.04	402	402	
solder	non noble metal	tin	7440-31-5	0.027	0.01		75		
	noble metal	silver	7440-22-4	0.033	0.01		93		
	non noble metal	lead	7439-92-1	1.268	0.36	0.38	3570	3738	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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